



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NUMBER C-171662

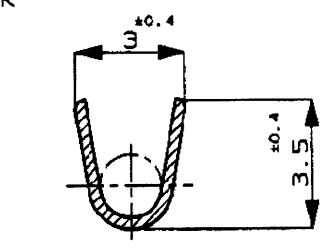
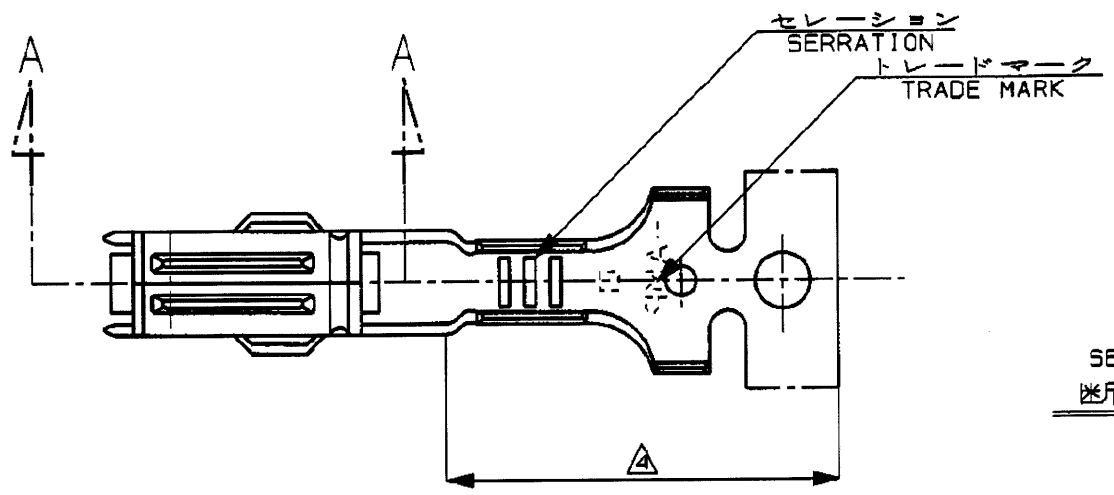
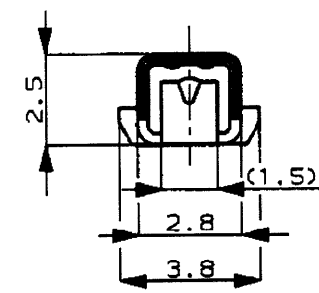
三角法 (3rd ANGLE PROJECTION)

METRIC

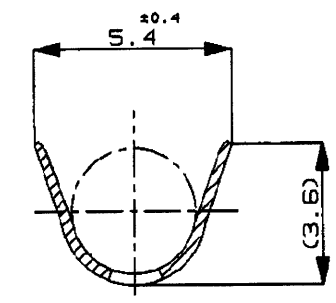
単位: 概 DIMENSIONS IN MM. DO NOT SCALE PRINT

PRINT DIST

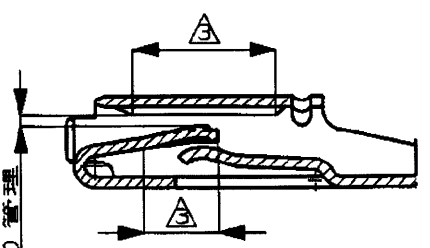
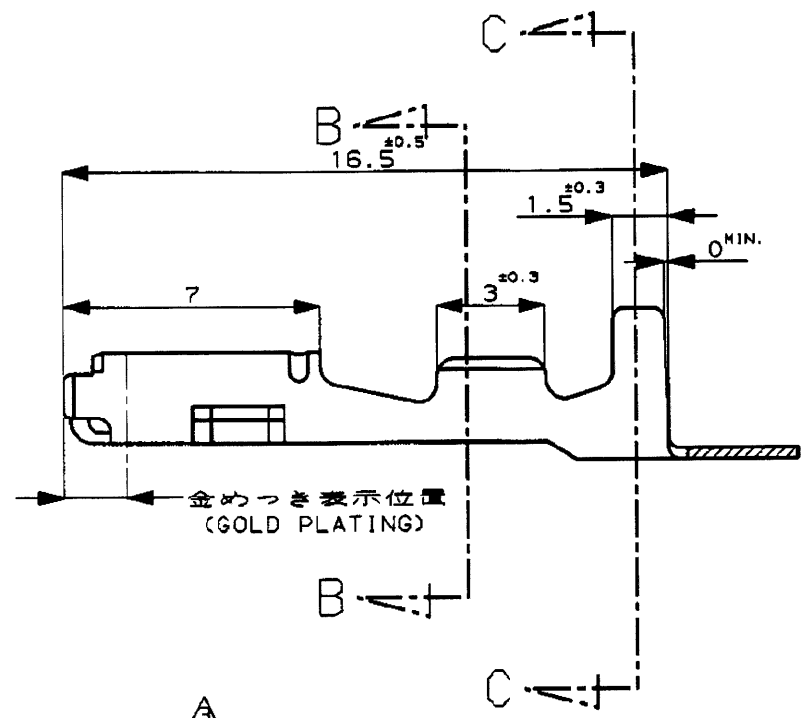
AMP-J REV.10/83



SECT. 断面 B-B



SECT. 断面 C-C



断面 A-A (尺度: 10-1) SCALE

注;

- 1. 嵌合相手端子型番 ; 171661
- 2. パラ状端子型番 ; 173707
- △ 部分金めつき 0.38 μm 最小
- △ 部分はんだめつき
- △ 部分金めつき 1.27 μm 最小

NOTE ;

- 1. TAB CONTACT ; 171661
- 2. L/P CONTACT ; 173707
- △ SELECTIVE GOLD PLATING 0.38 μm MIN.
- △ SELECTIVE TIN LEAD PLATING
- △ SELECTIVE GOLD PLATING 1.27 μm MIN.

OBSELETE	SELECTIVE GOLD PLATING AND SELECTIVE TIN LEAD PLATING	PHOS-BRONZE t0.3	1-171662-9
OBSELETE	△ 部分金めつき 及び 部分はんだめつき	リン青銅 板厚 0.3	
	SELECTIVE GOLD PLATING AND SELECTIVE TIN LEAD PLATING	PHOS-BRONZE t0.3	171662-9
	△ 部分金めつき 及び 部分はんだめつき	リン青銅 板厚 0.3	
	SELECTIVE GOLD PLATING	PHOS-BRONZE t0.3	171662-5
	△ 部分金めつき	リン青銅 板厚 0.3	
	PRE-TIN	PHOS-BRONZE t0.3	171662-4
	錫めつき済 (0.76μm MIN.)	リン青銅 板厚 0.3	
	PRE-TIN	BRASS t0.3	171662-1
	錫めつき済 (0.76μm MIN.)	黄銅 板厚 0.3	
	FINISH	MATERIAL	PART NUMBER
	仕上	材	型番

				STE TE Connectivity	
複合電線断面積 (WIRE RANGE) AVS AVS 0.5-1.25 mm ² (AWG20-16)		保護外皮 (INSULATION DIA.) 2-2.6 mmφ		名称 (NAME) ECONOSEAL J-MARKII ⁺ CONNECTOR RECEPTACLE CONTACT エコノシール J-マークII ⁺ リセプタクル コンタクト	
材料 (MATERIAL) SEE TABLE 表参照		仕上 (FINISH) SEE TABLE 表参照		一般公差 (GENERAL TOLERANCE) 10mm下: ±0.2 10mm以上 30mm下: ±0.25 30mm以上 100mm下: ±0.3 角 度: ±3°	
DR. K. Oda 7/16 '91		DE. K. Oda 7/16 '91		LOC 番号 (No.) B J C-171662	
LTR 変更 (REVISION RECORD)		CHK. S. S. 7/16 '91		尺度 (SCALE) REV. SHEET 5-1 F4 1 OF 1	

(CUSTOMER DRAWING) 参 考 面